

Attorney Docket No.: 111079-135918
IPN P14927X (Intel Corporation)

OCT 07 2005 Patent

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of:

Boggs, et al.

Application No.: 10/750,560

Filed: December 31, 2003

For: **Electronic Substrate with Direct
Inner Layer Component
Interconnection**

Examiner: Ishwarbhai B. Patel

Art Unit: 2841

Confirmation No. 5692

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AMENDMENT AND RESPONSE TO FINAL OFFICE ACTION

Dear Sir:

This communication is submitted in response to the Final Office Action mailed August 8, 2005. Applicants respectfully request reconsideration of the captioned application in view of the amendments and remarks to follow.

Amendments to the Specification – none;

Amendments to the Claims – are reflected in the listing of claims that begin on page 2 of this paper;

Amendments to the Drawings – none; and

Remarks/Arguments – begin on page 6 of this paper.

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